



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20190415001.0.A
Package Outline Drawing update for 176PBGA package
Information Only

Date: April 22, 2019
To: Newark/Farnell PCN

Dear Customer:

Revision A is to include page 2 regarding the device(s) affected by customer. We apologize for any inconvenience this may have caused.

This is an information-only announcement of a change to selected devices that are currently offered by Texas Instruments.

The changes discussed within this PCN are for customer information only. Please note that implementation may occur immediately after notification.

Any negotiated alternative change requirements will be provided via the customer's defined process. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services

20190415001.0.A
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TMS320F28235ZJZS	null
TMS320F28335ZJZA	null
TMS320F28335ZJZQ	null
TMS320F28335ZJZS	null

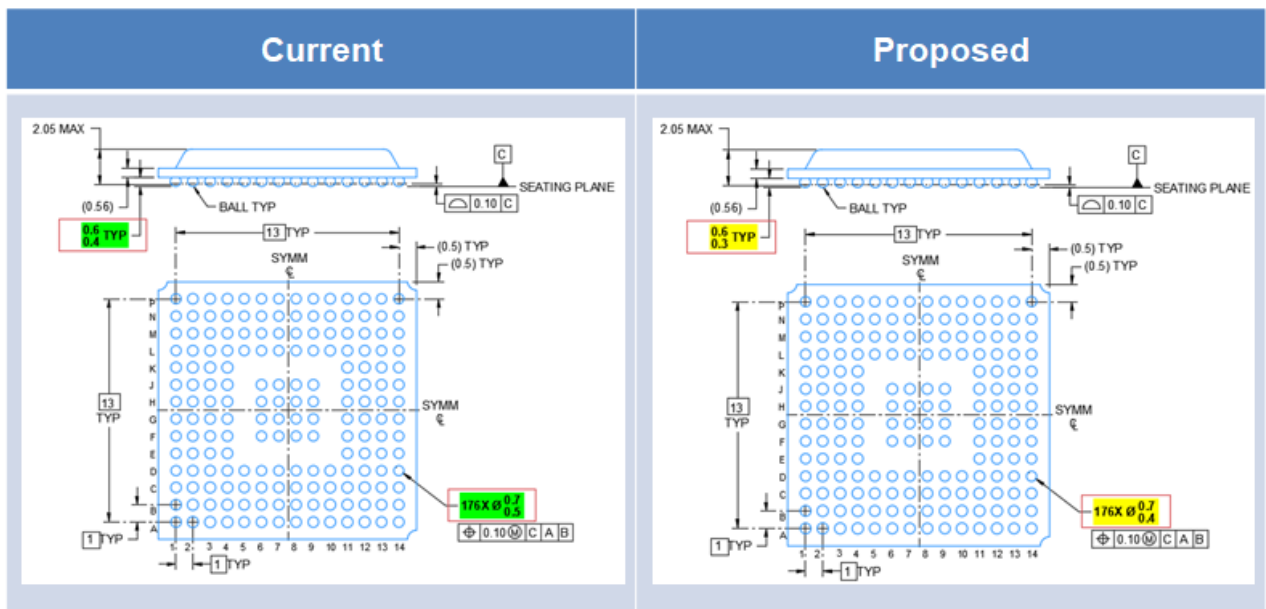
Technical details of this Product Change follow on the next page(s).

PCN Number:	20190415001.0.A	PCN Date:	Apr 22, 2019
Title:	Package Outline Drawing update for 176PBGA package		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Assembly Materials	
<input type="checkbox"/> Design	<input type="checkbox"/> Electrical Specification	<input checked="" type="checkbox"/> Mechanical Specification	
<input type="checkbox"/> Test Site	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/> Wafer Bump Material	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Wafer Fab Site	<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Wafer Fab Process	
	<input type="checkbox"/> Part number change		

PCN Details

Description of Change:

This notification is to inform of a Package Outline Drawing update for 176PBGA package Solder Ball specification as follows:



	Current	Proposed
Ball Diameter	0.5 – 0.7mm	0.4 – 0.7mm
Ball Height	0.4 – 0.6mm	0.3 – 0.6mm

Reason for Change:

Align package outline drawing for collapse solder ball between internal and external assembly sites

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

None

Product Affected:

C4780003GJZQ	SP320F28335ZJZQR	TMS320F28334ZJZA	TMS470R1VF478BGJZQ
C67A0001GJZQ	TMS320F28232ZJZA	TMS320F28334ZJZQ	TMS470R1VF478CGJZQ
C67A0002GJZQ	TMS320F28234ZJZA	TMS320F28334ZJZS	TMS470R1VF67ABGJZQ
C67A0003GJZQ	TMS320F28234ZJZQ	TMS320F28335ZJZA	TMS470R1VF67ACGJZQ
C67A0004GJZQ	TMS320F28234ZJZS	TMS320F28335ZJZQ	TMS470R1VF67ACZJZQ
S470AV67ACGJZQR	TMS320F28235ZJZA	TMS320F28335ZJZQCR	V62/09624-01XE
S470R1VF67ACZJZQQ1	TMS320F28235ZJZQ	TMS320F28335ZJZQR	
SA320F28335ZJZQ	TMS320F28235ZJZQR	TMS320F28335ZJZS	
SM320F28335GJZMEP	TMS320F28235ZJZS	TMS470R1VF356CGJZQ	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com